

Please cancel non-elected claims 23-29 without prejudice.

Please add the following new claims.

30. (new) A packaged integrated circuit, comprising:

a substrate having first and second opposing surfaces, said substrate comprising:

a plurality of signal lines, a plurality of first power lines, and a plurality of second power lines on said second surface, wherein one or more of said plurality of signal lines is between a pair of said plurality of first power lines, and further wherein said signal lines between said pair of said plurality of first power lines and said pair of said plurality of first power lines are between a pair of said second power lines;

an integrated circuit chip mounted on said substrate.

31. (new) The integrated circuit of Claim 30, wherein said signal lines are of a first width, said first power lines are of a second width, and said second power lines are of a third width.

32. The integrated circuit of Claim 31, wherein said third width is wider than said second width, and said second width is wider than said first width.

33. The integrated circuit of Claim 30, further comprising a ground plane on said first surface of said substrate.

34. (new) A packaged integrated circuit, comprising:

a substrate having first and second opposing surfaces, said substrate comprising:

a plurality of lines of at least three different widths on said second surface of said substrate, wherein said lines are arranged such that one or more

lines in a first set of lines of a first width are between lines of said second width, and such that one or more lines in a second set of lines of said second width are between lines of said third width;

an integrated circuit chip mounted on said substrate.

35. (new) The integrated circuit of Claim 34, wherein said lines of said first width are signal lines, said lines of said second width are power lines coupled to a first voltage potential, and said lines of said third width are power lines coupled to a second voltage potential.

36. (new) The integrated circuit of Claim 34, further comprising a ground plane on said first surface of said substrate.

REMARKS

Reconsideration of the above-referenced application in view of the amendments and the following remarks is respectfully requested.

Claims 1-29 were pending in this case. Non-elected claims 23-29 have been cancelled without prejudice. New claims 30-36 have been added. No amendments to the claims are made herein.

Claim 1 stands rejected under 35 U.S.C. 112. It was asserted in the Office Action that the phrase "said metal layers" at line 9 of Claim 1 lacks antecedent basis. Applicant respectfully traverses the rejection. Line 5 of claim 1 includes the feature "two patterned metal layers". The "one of said metal layers" limitation in line 9 is clearly referring to one of the two patterned metal layers. If the Examiner is still of the opinion that sufficient antecedent basis for the phrase does not exist, Applicant would welcome a suggestion by the Examiner as to how to improve upon the cited language.